



102081207

## PATENT

10/135419  
05/01/02

## PATENT

**RECORDATION FORM COVER SHEET  
CONTINUATION  
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U.S. Department of Commerce  
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**PATENT**

**Conveying Party(ies)**

7.  
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9.  
10.  
11.  
12.

**Execution Date(s)****Receiving Party(ies)**

Name RYODEN SEMICONDUCTOR SYSTEM ENGINEERING CORPORATION

Name

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Address Itami-shi

City

Hyogo-ken, Japan

State/Country

Zip Code

Name

Name

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City

State/Country

Zip Code

**Application Number(s) or Patent Number(s)**

☐ Mark if additional numbers attached

*Enter either the Patent Application Number or the Patent Number (DO NOT ENTER BOTH numbers for the same property).*

**Patent Application Numbers****Patent Numbers**

10,135,419

If this document is being filed together with a *new* Patent Application, enter the date the patent application was signed by the first named executing inventor.

Month Day Year  
April 15, 2002

**Patent Cooperation Treaty (PCT)**

Enter PCT application number *only* if a U.S. Application Number has not been assigned.

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## ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned,

Chigusa Yasuda and Akira Hamasaki

of c/o RYODEN SEMICONDUCTOR SYSTEM ENGINEERING CORPORATION,  
1, Mizuhara 4-chome, Itami-shi, Hyogo-ken, Japan

hereby sells, assigns and transfers to

mitsubishi denki kabushiki kaisha and  
RYODEN SEMICONDUCTOR SYSTEM ENGINEERING CORPORATION

of 2-3, Marunouchi 2-chome, Chiyoda-ku, Tokyo 100-8310 Japan and  
1, Mizuhara 4-chome, Itami-shi, Hyogo-ken, Japan, respectively

(hereinafter called the Assignee), its successors and assigns, the entire right, title, and interest in and to:

- (i) the application for United States Letters Patent entitled:  
METHOD FOR PREPARING MANUFACTURING PLAN AND METHOD FOR  
MANUFACTURING SEMICONDUCTOR PRODUCTS USING THE MANUFACTURING PLAN  
which was executed by the undersigned on  
April 15, 2002 or was filed on  
\_\_\_\_\_ and accorded Serial  
No. \_\_\_\_\_ (hereinafter called the Application);
- (ii) any and all inventions and improvements which are described in the Application;
- (iii) any and all United States Letters Patents which may be granted on the Application (hereinafter called the Patent);
- (iv) any and all divisions, continuations, substitutes, reexaminations, reissues, or extensions of the Application or Patent; and
- (v) all benefits under the International Convention for the Protection of Industrial Property.

The Assignee and its agents are hereby authorized to insert in this instrument the filing date and serial number of said application.

It is hereby authorized and requested that the Commissioner of Patents issue any and all of said Letters Patent, when granted, to said Assignee.

Further, it is agreed that, when requested, without charge to but at the expense of said Assignee, the undersigned will execute all divisional, continuing, substitute, or reissue patent applications; execute all additional assignments and other writings, including reexamination papers; and provide all reasonable assistance requested by the Assignee to secure and maintain appropriate patent protection.

Signed at Hyogo, Japan

this 15th day of April, 2002 .

WITNESS(ES):

Hiroshi Kamide

Toyoharu Shimoda

\_\_\_\_\_

\_\_\_\_\_

INVENTOR(S):

Chigusa Yasuda

Akira Hamasaki

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